CONSTRUCTION STANDARD SPECIFICATION

SECTION 09731

SEAMLESS STATIC CONDUCTIVE COVERING

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CONSTRUCTION STANDARD SPECIFICATION

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SEAMLESS STATIC CONDUCTIVE COVERING

PART 1 - GENERAL

1.01 SUMMARY

Extent of seamless conductive covering work is shown and scheduled on contract drawings. Provide static conductive seamless covering as a complete, integrated system consisting of bonding coat, body coat, sealer and grounding devices.

1.02 SUBMITTALS

- A. Material Safety Data Sheets (MSDS) on covering, leveling compound, and slab primers.
- B. Product test reports on the covering that shows compliance with the requirements of UL 779, NFPA 99, and ASTM E 84.
- C. Manufacturer's product specifications and installation instructions for each covering material. Include manufacturer's recommendations for cleaning and maintaining covering, including precautions against material and methods that may be detrimental to the covering.
- D. Installer experience qualification data.

1.03 QUALITY ASSURANCE

- A. Representative of the covering manufacturer shall test the installed covering and submit a written report to certify compliance with this specification, NFPA 99 and UL 779.
- B. Performance Requirements: Provide completed installation meeting the following requirements:
 - 1. Electrical Resistance: Take 5 or more readings in accordance with NFPA 99 at 50% RH and 70°F. Flooring shall have electrical resistance readings of 25,000 to 1,000,000 ohms between two electrodes as required by NFPA 99.
 - 2. Flame Spread: 25 or less when tested per ASTM E 84.
 - 3. Smoke Developed: 50 or less when tested per ASTM E 84.

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SEAMLESS STATIC CONDUCTIVE COVERING

1.04 DELIVERY, STORAGE, AND HANDLING

Deliver and store materials in manufacturer's original unopened packages, clearly marked with identifying information.

1.05 PROJECT CONDITIONS

- A. Temperature: Store materials at minimum temperature of 55°F for at least 24 hours prior to installation. In spaces where floors are being installed maintain at least 55°F from 48 hours before installation until 48 hours after installation. Do not mix materials if any component's temperature exceeds 89°F.
- B. Ventilation: Follow the MSDS for proper ventilation, or the manufacturer's recommendations, whichever is more conservative.
- C. Protection: Schedule seamless covering to minimize the amount of subsequent work that must be done in the area. When work must be done over seamless flooring, cover flooring with a suitable protective covering approved by the Sandia Delegated Representative (SDR).

PART 2 - PRODUCTS

2.01 COVERING

Covering shall be Dex-O-Tex Conductive Terrazzo or Dex-O-Tex Conductive Neotex-367 or approved equal quality. Dex-O-Tex is manufactured by Crossfield Products Corp., 3000 E. Harcourt Street, Rancho Dominguez, California 90221 (310) 886-9100.

2.02 FLOOR ACCESSORIES

- A. Integral Cove Base: Follow the manufacturer's application instructions in forming the cove base.
- B. Reducing Strips: Furnish vinyl or rubber reducing (edge) strips at all exposed edges of floor covering, no less than 1 inch wide with a beveled forward edge, of the same thickness as floor covering material. Furnish color to be compatible with floor.

2.03 LEVELING COMPOUND

Latex type as recommended by covering manufacturer.

2.04 MISCELLANEOUS MATERIALS

Furnish concrete slab primers and other materials as recommended in writing by the manufacturer of the conductive covering.

PART 3 - EXECUTION

3.01 SUBSURFACE EXAMINATION

- A. Assure that subsurface presents a smooth, even plane suitable for installation of covering material.
- B. Investigate subsurface to determine moisture content and other conditions that might harmfully affect the finished covering.
- C. Assure that subsurface is clean and free of paint, oil, wax or other harmful materials.

3.02 SUBSURFACE PREPARATION

- A. Follow manufacturer's printed directions.
- B. Fill cracks, rough areas and similar surface defects with plastic material. Grind away high spots and fill depressions to establish smooth planes.
- C. Where fill depth exceeds 1/8 inch, apply underlayment in 1/8 inch layers, each layer feather-edged and allowed to set.
- D. Apply subsurface primer if recommended by covering manufacturer covering, prior to application of bond coat, in compliance with manufacturer's printed directions.

3.03 INSTALLATION

Apply materials with notched trowels to maintain the proper depth. Apply each coat at the manufacturer's recommended rate and thickness. Protect adjacent walls and floors during seamless floor covering installation.

- A. Reference markers: Maintain reference markers, holes or openings that are in place or plainly marked for future cutting by repeating on the covering as marked on the sub-surface.
- B. Application: Apply conductive covering to work benches, shelving, chairs and stools to the extent indicated on the contract drawings..
- C. Repair: Repair damaged areas as directed by the SDR.

3.04 CLEANING

After installation is completed, thoroughly clean the covering in accordance with manufacturer's maintenance recommendations.

END OF SECTION